

**Amendments to the Claims**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1-5. (Canceled)

6. (Currently amended) A method for preventing electrostatic damages to a semiconductor chip package during storage, the package having a plurality of terminals, the method comprising:

forming one or more conductive members electrically connecting the terminals to each other, thereby short-circuiting the terminals so that voltage is not applied to the semiconductor chip package; and

disabling the electrical connections by an action of mounting the package on a printed circuit board, wherein the electrical connections are melted by a heat of soldering the terminals so that operation of the semiconductor chip package is not obstructed.

7. (Original) The method of claim 6, wherein the step of forming the conductive members comprises forming solder members connecting the terminals, and wherein the action of mounting the package comprises soldering the terminals.

8. (Original) The method of claim 7, wherein the step of forming the conductive members comprises forming solder lines connecting the terminals.

9. (Original) The method of claim 7, wherein the step of forming the conductive members comprises forming a conductive thin film.

10. (Original) The method of claim 6, wherein the terminals are pin-shaped having protruding tips, and the step of forming the conductive members comprises forming conductive wires connected at the tips of the terminals, and wherein the action of mounting the package comprises inserting the terminals into sockets.

11. (Canceled)

12. (Previously presented) The method of claim 9, wherein the step of forming the conductive thin film comprises patterning the conductive thin film by a photolithography process and an etching process.

13. (Previously presented) The method of claim 8, wherein the solder lines are formed to a net-like structure.

14. (Previously presented) The method of claim 8, wherein the solder lines are formed to a single line-like solder member.

15. (Previously presented) The method of claim 9, wherein the step of forming the conductive thin film comprises forming the conductive thin film on the terminals.